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ABSTRACT OF THE DISCLOSURE

5 An apparatus for removing fluorinated and chlorinated
compounds contained in waste gas streams from semiconductor
etch and deposition processes. The apparatus has a
treatment chamber in which a plurality of liquid films are
10 formed to absorb the fluorinated and chlorinated compounds
contained in the waste gas streams that pass through the
liquid films. The apparatus includes a tank for receiving
the mixture of the absorbed fluorinated and chlorinated
compounds and the liquid, and a dehumidifying device for
15 stabilizing and dehumidifying the humidified waste gas
streams.